## What is claimed is:

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1 1.	Α	function	module	comprising:
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- a circuit board including a surface;
- a first device disposed on the surface;
  - a second device disposed on the surface, wherein the height of the second device is higher than the height of the first device; and
  - a planarization member, including a flat surface, disposed on the surface in a manner such that the first device and the second device is surrounded by the planarization member, wherein the height of the flat surface is not less than the height of the second device; and
  - a plate-type heat dissipation device disposed on the flat surface.
- The function module as claimed in claim 1, wherein the planarization member is made of insulating material.
- 3. The function module as claimed in claim 2, wherein the insulating material is a thermosetting polymer.
- 4. The function module as claimed in claim 3, wherein the insulating material comprises one selected from the group consisting of polyimide, silicone and the combination thereof.

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- 5. The function module as claimed in claim 2, wherein the planarization member further includes a thermal-conductive material.
  - 6. The function module as claimed in claim 5, wherein the thermal-conductive material comprises one selected from the group consisting of AlN, SiC, BN, ZnO and the combination thereof.
    - 7. The function module as claimed in claim 1, wherein the plate-type heat dissipation device is a plate-type heat pipe, a micro fin, a vapor chamber, or a water-cooling device.
      - 8. The function module as claimed in claim 1, wherein the second device is a CPU.
- 9. A method for manufacturing a function module, comprising:
  - providing a circuit board and a plate-type heat dissipation device, wherein the circuit board includes a plurality of devices with varying heights thereon;
  - placing a planarization member on the circuit board so that the devices are surrounded by the planarization member;
  - curing the planarization member so as to form a flat surface, wherein the height of the flat surface is not less than the height of the devices; and placing the plate-type heat dissipation device on the flat surface.

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- 10. The method as claimed in claim 9, wherein the 2 planarization member is made of insulating material.
- 1 11. The method as claimed in claim 10, wherein the insulating material is a thermosetting polymer.
  - 12. The method as claimed in claim 11, wherein the insulating material comprises one selected from the group consisting of polyimide, silicone and the combination thereof.
- 1 13. The method as claimed in claim 10, wherein the planarization member further includes a thermalconductive material.
  - 14. The method as claimed in claim 13, wherein the thermal-conductive material comprises one selected from the group consisting of AlN, SiC, BN, ZnO and the combination thereof.
    - 15. The method as claimed in claim 9, wherein the planarization member is covered by two protective layers, and the protective layers are disposed at opposite sides of the planarization member in a detachable manner.
    - of the protective layers is separated from the planarization member before the planarization member is disposed on the circuit board, and another protective layer is separated from the planarization member before the planarization member before the planarization member is cured.

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- 17. The method as claimed in claim 15, wherein one of protective layers is separated from the the planarization member before the planarization member is disposed on the circuit board, and another protective layer is separated from the planarization member after the planarization member is cured.
  - The method as claimed in claim 9, wherein the 18. plate-type heat dissipation device is a plate-type heat pipe, a micro fin, a vapor chamber, or a water-cooling device.
- The method as claimed in claim 9, wherein the 1 planarization member is heating cured by the 2 planarization member. 3
- 20. The method as claimed in claim 9, wherein the planarization member is infrared 2 cured by light irradiation.
  - 21. The method as claimed in claim 9, wherein the planarization member is cured by ultraviolet irradiation.
- 22. A method for manufacturing a function module, 1 comprising: 2

providing a circuit board and a plate-type heat dissipation device, wherein the circuit board includes a plurality of devices with varying heights thereon; 6

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- placing a planarization member on the circuit board

  so that the devices are surrounded by the

  planarization member;

  forming a flat surface on the planarization member,

  wherein the height of the flat surface is not
  - placing the plate-type heat dissipation device on the flat surface.

less than the height of the devices; and

- 23. The method as claimed in claim 22, wherein the planarization member is made of insulating material.
  - 24. The method as claimed in claim 23, wherein the insulating material is a thermosetting polymer.
  - 25. The method as claimed in claim 24, wherein the insulating material comprises one selected from the group consisting of polyimide, silicone and the combination thereof.
    - 26. The method as claimed in claim 23, wherein the planarization member further includes a thermal-conductive material.
    - 27. The method as claimed in claim 26, wherein the thermal-conductive material comprises one selected from the group consisting of AlN, SiC, BN, ZnO and the combination thereof.
    - 28. The method as claimed in claim 22, wherein the planarization member is covered by a protective layer and the plate-type heat dissipation device, and the protective layer and the plate-type heat dissipation

- device are disposed at opposite sides of the planarization member.
- 29. The method as claimed in claim 28, wherein the protective layer is separated from the planarization member before the planarization member is disposed on the circuit board.
- 30. The method as claimed in claim 22, wherein the plate-type heat dissipation device is a plate-type heat pipe, a micro fin, a vapor chamber, or a water-cooling device.